

ORGALLOY[®]

EM 067 HSP

Orgalloy[®] EM 067 HSP resin is a flexible polyamide designed to be used for refrigerant barrier layer in air conditioning rubber hose.

Packaging:

This grade is delivered dried in sealed packaging (20kg bags) ready to be processed.

Shelf life:

Two years from the date of delivery. For any use above this limit, please refer to our technical services.

特性	乾燥/調湿	単位	テスト基準
レオロジー特性			
メルトポリュームレイト	1 / *	cm ³ /10min	ISO 1133
温度	235 / *	°C	-
	455 / *	°F	-
荷重	5 / *	kg	-
	11 / *	lb	-
機械的特性			
引張弾性率	- / 572	MPa	ISO 527-1/-2
	- / 83000	psi	
50%ひずみ時応力	- / 32	MPa	ISO 527-1/-2
	- / 4640	psi	
破壊ひずみ	- / >50	%	ISO 527-1/-2
熱的特性			
溶融温度, 10°C/min	215 / *	°C	ISO 11357-1/-3
その他の特性			
密度	1140 / 1140	kg/m ³	ISO 1183
	1.14 / 1.14	g/cm ³	

Processing conditions:

- Drying time (only necessary for bags opened for more than two hours): 4-16 hours at 80-90°C
- Extrusion melt temperature (min-recommended-max): 240-260-300°C

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成形加工法 フィルム押出成形, 異形押出成形, その他の押出成形	Headquarters: Arkema France 420 rue d'Estienne d'Orves 92705 Colombes Cedex France T +33 (0)1 49 00 80 80 hpp.arkema.com Arkema Inc. – High Performance Polymers 900 First Avenue King of Prussia, PA 19406 Tel.: +1 610 205 7000 hpp.arkema.com
納入形状 ペレット	
添加剤 可塑剤	
領域別の利用可能性 北アメリカ, ヨーロッパ, アジア/太平洋地域, 南・中央アメリカ, 近東/アフリカ	

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